



SEMITRANS® 4

IGBT4 Modules

SKM900GA12E4

Target Data

Features

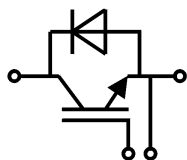
- IGBT4 = 4. Generation Medium Trench IGBT (Infineon)
- CAL4 = Soft switching 4. Generation CAL-Diode
- Isolated copper baseplate using DBC Technology (Direct Copper Bonding)
- UL recognized, file no. E63532
- Increased power cycling capability
- With integrated Gate resistor
- For switching frequencies up to 12kHz

Typical Applications*

- AC inverter drives
- UPS
- Electronic welders
- Switched reluctance motor

Remarks

- Case temperature limited to $T_c = 125^\circ\text{C}$ max, recomm. $T_{op} = -40 \dots +150^\circ\text{C}$, product rel. results valid for $T_j = 150^\circ$



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Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
IGBT				
V _{CES}	T _j = 25 °C		1200	V
I _C	T _j = 175 °C	T _c = 25 °C	1305	A
		T _c = 80 °C	1003	A
I _{Cnom}			900	A
I _{CRM}	I _{CRM} = 3xI _{Cnom}		2700	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 800 V V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _j = 150 °C	10	μs
T _j			-40 ... 175	°C

Inverse diode

I_F	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	871	A
		$T_c = 80^\circ\text{C}$	651	A
I_{Fnom}			800	A
I_{FRM}	$I_{FRM} = 3 \times I_{Fnom}$		2400	A
I_{FSM}	$t_p = 10\text{ ms, sin } 180^\circ, T_j = 25^\circ\text{C}$		3520	A
T_j			-40 ... 175	$^\circ\text{C}$

Module

$I_{t(RMS)}$	$T_{terminal} = 80^\circ\text{C}$	500	A
T_{stg}		-40 ... 125	$^\circ\text{C}$
V_{isol}	AC sinus 50 Hz, $t = 1\text{ min}$	4000	V

Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
IGBT					
$V_{CE(sat)}$	$I_C = 900\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.83	2.08	V
		$T_j = 150^\circ\text{C}$	2.23	2.44	V
V_{CE0}	chipelevel	$T_j = 25^\circ\text{C}$	0.8	0.9	V
		$T_j = 150^\circ\text{C}$	0.7	0.8	V
r_{CE}	$V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.14	1.31	$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$	1.70	1.82	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 32.8\text{ mA}$	5	5.8	6.5	V
I_{CES}	$V_{GE} = 0\text{ V}$ $V_{CE} = 1200\text{ V}$	$T_j = 25^\circ\text{C}$	0.1	0.3	mA
		$T_j = 150^\circ\text{C}$			mA
C_{ies}	$V_{CE} = 25\text{ V}$ $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	54.4		nF
C_{oes}		$f = 1\text{ MHz}$	3.52		nF
C_{res}		$f = 1\text{ MHz}$	3		nF
Q_G	$V_{GE} = -8\text{ V} \dots +15\text{ V}$		5100		nC
R_{Gint}	$T_j = 25^\circ\text{C}$		0.94		Ω
$t_{d(on)}$	$V_{CC} = 600\text{ V}$	$T_j = 150^\circ\text{C}$	200		ns
t_r	$I_C = 900\text{ A}$	$T_j = 150^\circ\text{C}$	100		ns
E_{on}	$V_{GE} = \pm 15\text{ V}$ $R_{G on} = 0.5\text{ }\Omega$	$T_j = 150^\circ\text{C}$	80		mJ
$t_{d(off)}$	$R_{G off} = 0.5\text{ }\Omega$	$T_j = 150^\circ\text{C}$	620		ns
t_f	$di/dt_{on} = 9000\text{ A}/\mu\text{s}$ $di/dt_{off} = 4500\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$	110		ns
E_{off}		$T_j = 150^\circ\text{C}$	115		mJ
$R_{th(j-c)}$	per IGBT			0.035	K/W



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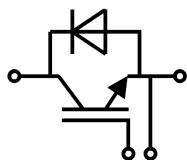
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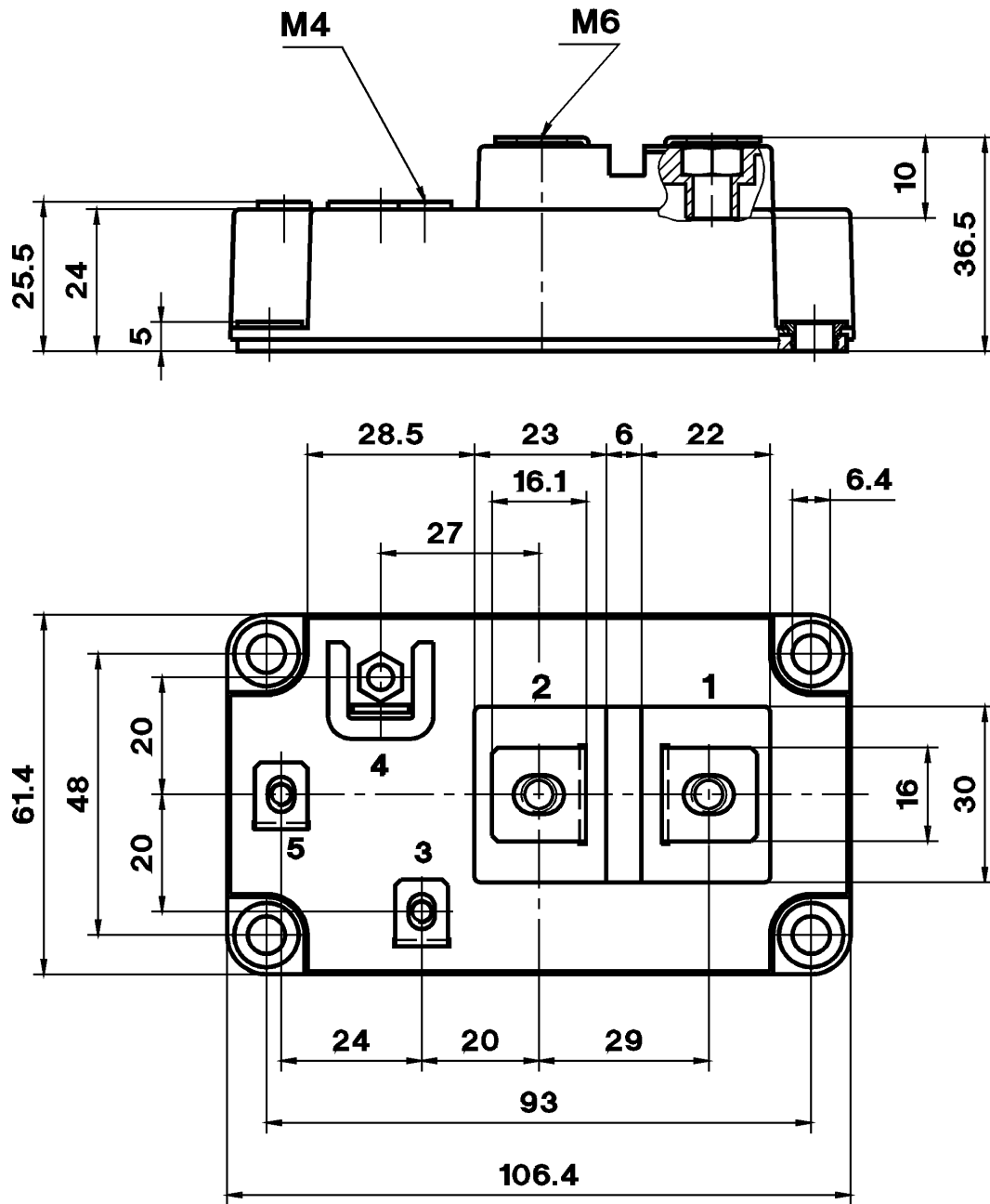
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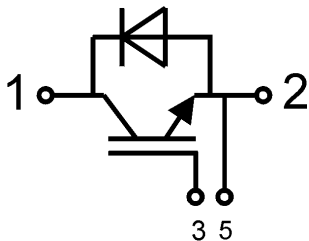
Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
V _F = V _{EC}	I _F = 900 A	T _j = 25 °C		2.31	2.65	V
	V _{GE} = 0 V chiplevel	T _j = 150 °C		2.31	2.64	V
V _{F0}	chiplevel	T _j = 25 °C		1.3	1.5	V
		T _j = 150 °C		0.9	1.1	V
r _F	chiplevel	T _j = 25 °C		1.1	1.3	mΩ
		T _j = 150 °C		1.6	1.7	mΩ
I _{RRM}	I _F = 900 A	T _j = 150 °C		850		A
Q _{rr}	di/dt _{off} = 9000 A/μs	T _j = 150 °C		140		μC
E _{rr}	V _{GE} = ±15 V V _{CC} = 600 V	T _j = 150 °C		65		mJ
R _{th(j-c)}	per diode				0.07	K/W
Module						
L _{CE}				15	20	nH
R _{CC'+EE'}	terminal-chip	T _C = 25 °C		0.18		mΩ
		T _C = 125 °C		0.22		mΩ
R _{th(c-s)}	per module			0.02	0.038	K/W
M _s	to heat sink M6		3		5	Nm
M _t	to terminals	M6	2.5		5	Nm
		M4	1.1		2	Nm
w					330	g



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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.